

Call for Papers - EXTENDED



Innovations enabled by Flexible Electronics

Co-located with  **electronica**

Invitation

End users, supply chain companies, R&D organizations, start-ups and universities are invited to submit abstracts for the 2018 FLEX Europe Conference. FLEX Europe Conference will be held in cooperation with Fraunhofer EMFT's forum BE-FLEXIBLE. This two half-day conference, an integral part of SEMICON Europa 2018 co-located with electronica, will address materials, manufacturing, new technologies and applications for flexible hybrid electronics (FHE) and printed electronics (PE) and will demonstrate the strong history of Europe in the field.

FLEX Europe 2018 Theme Description

By co-locating with Europe's largest semiconductor manufacturing event and held in cooperation with the Fraunhofer EMFT's forum be-flexible forum, the FLEX Europe Conference focuses on the integration of a whole new class of flexible hybrid electronics enabled by integration of conventional semiconductor devices with thin and flexible form factor with flexible electronic substrates, materials and processing techniques. Key technical topics are expected to be covered such as Thin Silicon, Flexible Sensors, Heterointegration on Flex, Bendable Electronics, New materials and Reliability of Flexible Electronics. Markets being impacted by flexible hybrid electronics include structural health monitoring, the Internet of Things (IOT), smart systems for sport, wellness and medical, among others. Specific applications include wearable electronics, smart packaging, smart sensor systems, and physiological monitoring devices.

2018 FLEX Europe – be flexible Conference – Recommended List of Topics for Presentations

Business Strategies & Market Overview

- Emerging Markets
- Perspective for Flexible Electronics
- Technology Roadmap
- Funding Programs

Integration Processes on Flex

- Thin Silicon, Thin Wafer, Die Handling
- Roll-to-Roll Processing
- System Integration / Heterogeneous Integration
- Equipment & Tools
- Metrology, Testing & Reliability
- Scale-up for Production

Materials and Components	Applications
<ul style="list-style-type: none"> ▪ Substrates, Films and Textiles ▪ Polymers, Functional Inks, Semiconductors ▪ Bio-compatible/ degradable & recyclable Materials ▪ Sensors on Flex ▪ Flexible Displays ▪ Energy Sources 	<ul style="list-style-type: none"> ▪ Wearables and Stretchables ▪ Healthcare, Assisted Living ▪ Internet of Things Sensor Nodes ▪ Human Machine Interfaces, Robotics, Electronic Skin ▪ Smart Buildings, Condition Monitoring ▪ Smart Packaging ▪ Automotive, Avionics, Transportation

Instructions to submit an abstract

To submit your abstract please click [here](#).

General guidelines:

- Review the list of recommended topics on Page 1
- Please submit your abstracts, biography and a photo via internet until **18 May 2018**. Abstracts submitted via fax, e-mail, post, or other methods will generally not be accepted.
- The conference language is English.
- The abstract should have between 1.000 and 2.000 characters (Starting with descriptive paragraph identifying issue addressed and solution).
- Abstract changes and corrections will be accepted until the **18 May 2018**.

Your presentation may not be included in the review process unless the information is complete.

Evaluation criteria include significance, usefulness for the manufacturing world and clarity and accuracy as a paper. Abstracts will be peer-reviewed and selected relative to the points above. We encourage application related presentations, i.e., on joint projects between users and suppliers. Papers are to be non-commercial and focus on the technical/economical merits of a process rather than the individual company's product benefits.

Deadline: Submit your abstracts and biography until **18 May 2018**.

Changes: After your first registration, your data are saved. Changes can be made any time until **18 May 2018**.

Notification: Selected presenters will be notified by **20 July 2018**.

With best regards from the Flex Europe Committee,

Committee members:

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| • Karl-Heinz Bock, Technische Universität Dresden | Indranil Ronnie Bose, Fraunhofer EMFT |
| • Michael Ciesinski, FlexTech Alliance | Istvan Denes, Bosch |
| • Jerome Gavillet, Cea-Liten | Mike Hack, Universal Display Corp. (UDC) |
| • Heidi Hoffman, SEMI | Ryoichi Ishihara, TU Delft |
| • Helen Kardan, TNO | Antti Kemppainen, VTT |
| • Christoph Kutter, Fraunhofer EMFT (chairman) | Christof Landesberger, Fraunhofer EMFT |
| • Luigi Occhipinti, Univ. of Cambridge | Frank Schulte, AIXTRON SE |
| • Andreas Toennis, AIXTRON SE | Andre Zimmermann, Universität Stuttgart / Hahn-Schickard-Gesellschaft |